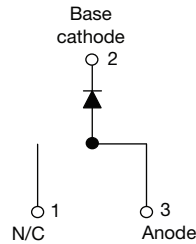


High Performance Schottky Rectifier, 8 A



D2PAK (TO-263AB)



FEATURES

- 175 °C T_J operation
- Low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified meets JESD 201 class 1A whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY

$I_{F(AV)}$	8 A
V_R	80 V, 100 V
V_F at I_F	0.58 V
I_{RM}	7 mA at 125 °C
T_J max.	175 °C
E_{AS}	7.5 mJ
Package	D2PAK (TO-263AB)
Diode variation	Single

DESCRIPTION

The VS-8TQ... Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	8	A
V_{RRM}	Range	80/100	V
I_{FSM}	$t_p = 5 \mu s$ sine	850	A
V_F	8 A _{pk} , $T_J = 125$ °C	0.58	V
T_J	Range	-55 to +175	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-8TQ080SHM3	VS-8TQ100SHM3	UNITS
Maximum DC reverse voltage	V_R	80	100	V
Maximum working peak reverse voltage	V_{RWM}			

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 157$ °C, rectangular waveform	8	A
Maximum peak one cycle non-repetitive surge current See fig. 7	I_{FSM}	5 μs sine or 3 μs rect. pulse	850	A
		10 ms sine or 6 ms rect. pulse	230	
Non-repetitive avalanche energy	E_{AS}	$T_J = 25$ °C, $I_{AS} = 0.50$ A, $L = 60$ mH	7.50	mJ
Repetitive avalanche current	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical	0.50	A



ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS	
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	8 A	$T_J = 25\text{ }^{\circ}\text{C}$	0.72	V	
		16 A		0.88		
		8 A	$T_J = 125\text{ }^{\circ}\text{C}$	0.58		
		16 A		0.69		
Maximum reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{Rated } V_R$	0.55	mA	
		$T_J = 125\text{ }^{\circ}\text{C}$		7		
Maximum junction capacitance	C_T	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^{\circ}\text{C}$		500	pF	
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		8	nH	
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/ μ s	

Note
⁽¹⁾ Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to 175	°C
Maximum thermal resistance, junction to case		R _{thJC}	DC operation See fig. 4	2.0	°C/W
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased	0.50	
Approximate weight				2	g
				0.07	oz.
Mounting torque	minimum			6 (5)	kgf · cm (lbf · in)
	maximum			12 (10)	
Marking device		Case style D2PAK	8TQ080SH		
			8TQ100SH		

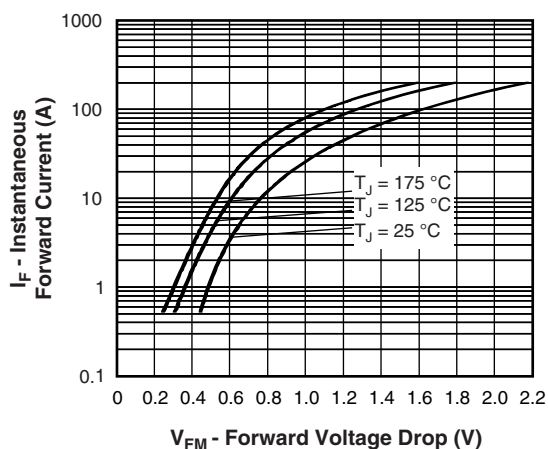


Fig. 1 - Maximum Forward Voltage Drop Characteristics

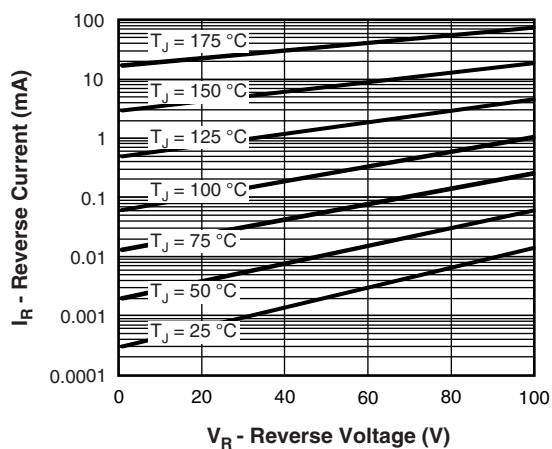


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

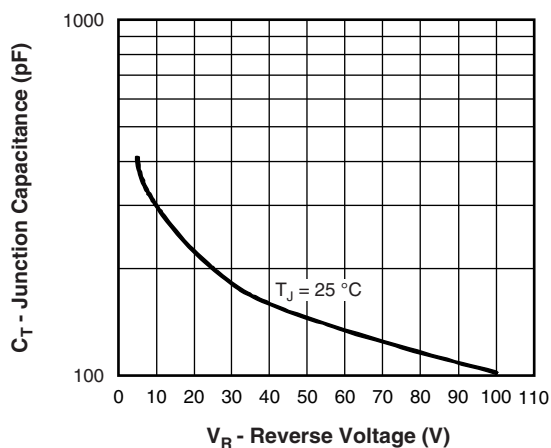
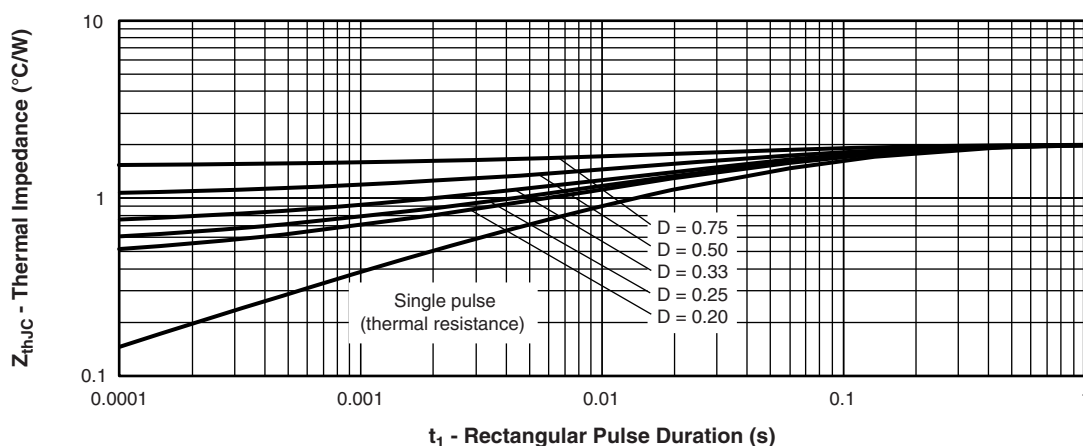


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

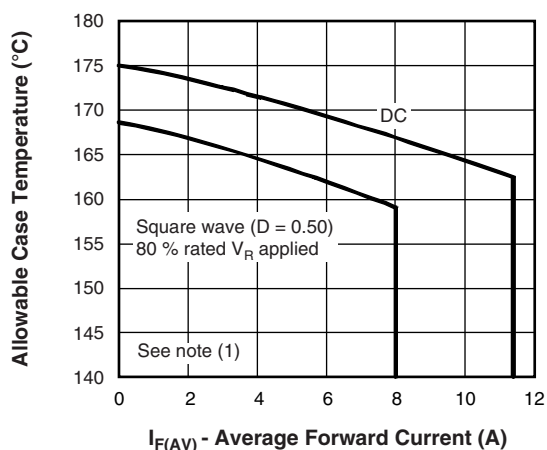


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

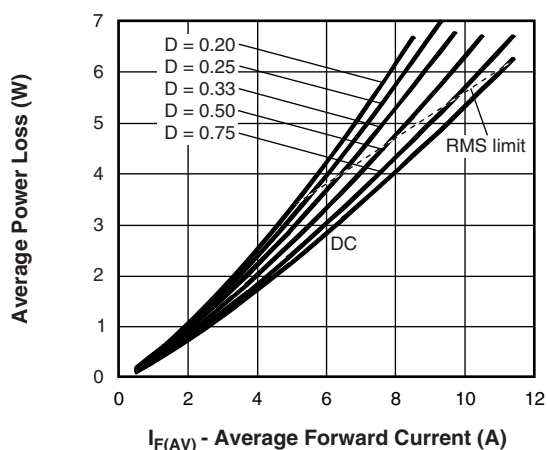


Fig. 6 - Forward Power Loss Characteristics

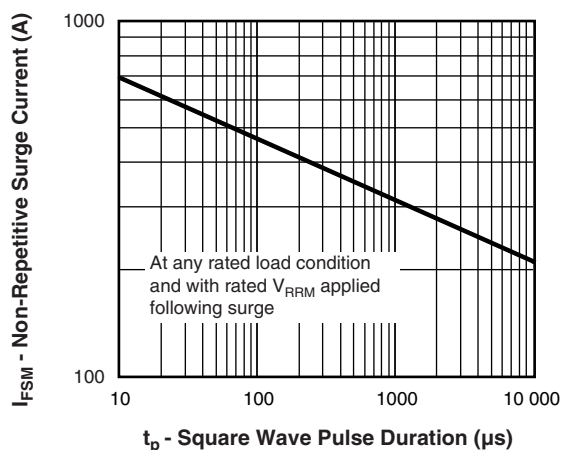


Fig. 7 - Maximum Non-Repetitive Surge Current

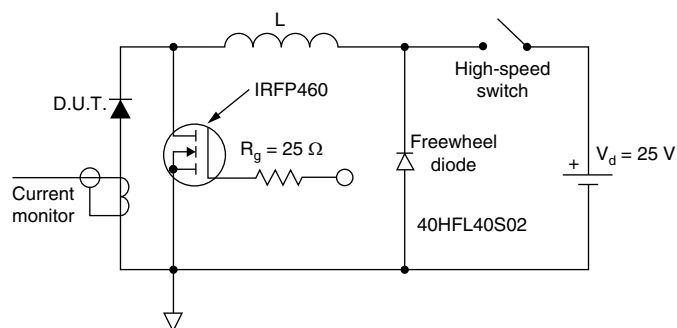


Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R

**ORDERING INFORMATION TABLE**

Device code	VS-	8	T	Q	100	S	TRL	H	M3
	1	2	3	4	5	6	7	8	9
1	- Vishay Semiconductors product								
2	- Current rating (8 A)								
3	- Circuit configuration: T = TO-220								
4	- Schottky "Q" series								
5	- Voltage ratings								
6	- S = D2PAK								
7	- <ul style="list-style-type: none">• None = tube• TRL = tape and reel (left oriented)• TRR = tape and reel (right oriented)								
8	- H = AEC-Q101 qualified								
9	- M3 = Halogen-free, RoHS-compliant, and termination lead (Pb)-free								

080 = 80 V
100 = 100 V

ORDERING INFORMATION			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8TQ080SHM3	50	1000	Antistatic plastic tubes
VS-8TQ080STRRH3	800	800	13" diameter reel
VS-8TQ080STRLH3	800	800	13" diameter reel
VS-8TQ100SHM3	50	1000	Antistatic plastic tubes
VS-8TQ100STRRH3	800	800	13" diameter reel
VS-8TQ100STRLH3	800	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95444
Packaging information	www.vishay.com/doc?95032
SPICE model	www.vishay.com/doc?96227



D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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